

Amendments to the CLAIMS:

Without prejudice, this listing of the claims replaces all prior versions and listings of the claims in the present application:

LISTING OF CLAIMS:

1-12. (Canceled)

13. (Currently Amended) A micropatterned thermosensor, comprising:

a supporting body; and

at least one thermocouple located on the supporting body, the thermocouple including a first material and a second material which form at least in a point-wise manner, at least one thermal contact with each other, at least one of the first material and the second material at least regionally configured in the form of one of a meander-shaped and an [[undulating-type]] undulating circuit trace and arranged on the supporting body;

wherein the first material and the second material extend one of substantially side-by-side in the form of circuit traces, the first material and the second material electrically insulated from one another with the exception of thermal contacts, and extend over one another at least regionally in the form of circuit traces, the first material and the second material electrically insulated from one another with the exception of thermal contacts;

wherein the thermocouple includes a plurality of thermal contacts configured as one of a thermal chain and a thermal column, at least two of the thermal contacts to different temperatures; and

wherein a first one of the thermal contacts is exposed to a first temperature, the first temperature kept one of constant and at least approximately constant, and a second one of the thermal contacts is exposed to a second temperature, the second temperature to be one of detected and measured, the thermosensor further comprising an additional measuring device configured to detect the first temperature.

14. (Previously Presented) The micropatterned thermosensor according to claim 13, wherein the micropatterned thermosensor includes an infrared sensor.

15. (Canceled)

16. (Canceled)

17. (Canceled)

18. (Currently Amended) The micropatterned thermosensor according to claim ~~[[17]]~~ 13, wherein the measuring device one of includes a part ~~[[of one]]~~ of one of the circuit traces, arranged in the vicinity of one of the first thermal contact, and of a conductor and includes a reference circuit trace as a sensitive component, arranged in a vicinity of the first thermal contact, and wherein the measuring device includes an evaluation arrangement configured to determine a temperature dependent, electrical resistance of one of the part of the trace, the conductor and the reference circuit trace.

19. (Previously Presented) The micropatterned thermosensor according to claim 13, wherein at least one of the first and the second material includes a material having low thermal conductivity.

20. (Previously Presented) The micropatterned thermosensor according to claim 13, wherein the first and the second material includes at least one of platinum, gold, lead tellurides, aluminum, titanium, polysilicon, doped polysilicon, polysilicon-germanium, and doped polysilicon-germanium.

21. (Previously Presented) The micropatterned thermosensor according to claim 20, wherein the first material includes one of doped and undoped polysilicon-germanium and the second material includes platinum.

22. (Currently Amended) The micropatterned thermosensor according to claim 18, wherein ~~[[the]]~~ one of the part of the circuit trace, the conductor and the reference circuit trace includes a platinum circuit trace.

23. (Currently Amended) A micropatterned thermosensor, comprising:

a supporting body; and

at least one thermocouple located on the supporting body, the thermocouple including a first material and a second material, which form at least in a point-wise manner at least one thermal contact with each other, the second material including platinum and the first material including one of doped and undoped polysilicon-germanium;

wherein the first material and the second material extend one of substantially side-by-side in the form of circuit traces, the first material and the second material electrically insulated from one another with the exception of thermal contacts, and extend over one another at least regionally in the form of circuit traces, the first material and the second material electrically insulated from one another with the exception of thermal contacts;

wherein the thermocouple includes a plurality of thermal contacts configured as one of a thermal chain and a thermal column, at least two of the thermal contacts exposed to different temperatures; and

wherein a first one of the thermal contacts is exposed to a first temperature, the first temperature kept one of constant and at least approximately constant, and a second one of the thermal contacts is exposed to a second temperature, the second temperature to be one of detected and measured, the thermosensor further comprising an additional measuring device configured to detect the first temperature.

24. (Previously Presented) The micropatterned thermosensor according to claim 23, wherein the micropatterned thermosensor includes an infrared sensor.

25. (Currently Amended) The micropatterned thermosensor according to claim 23, wherein at least one of the first material and the second material is configured at least regionally in a form of one of a meander-shaped and an [[undulating-type]] undulating circuit trace and extends on the supporting body.

26. (Previously Presented) The micropatterned thermosensor according to claim 23, wherein the thermocouple includes a plurality of contacts configured as one of a thermal chain and a thermal column, at least two thermal contacts exposed to different temperatures.